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News Release

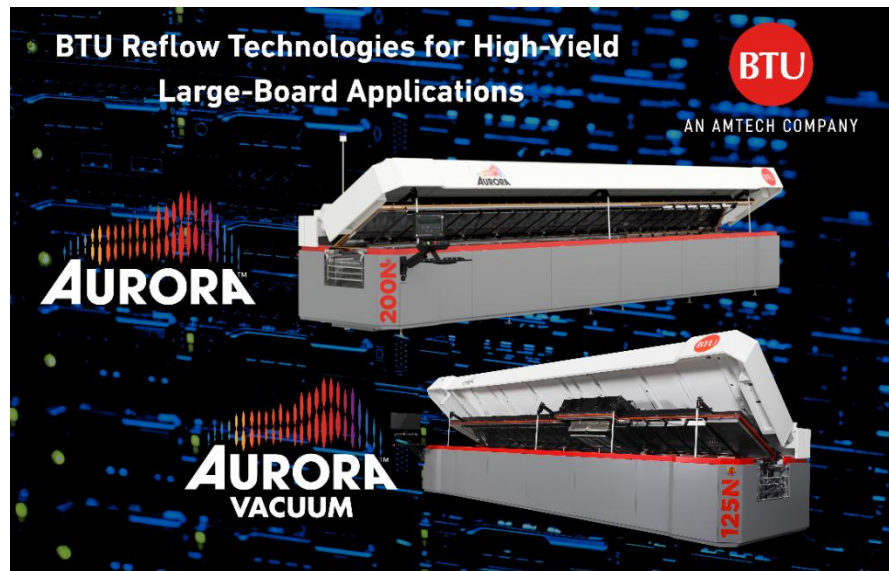
FOR IMMEDIATE RELEASE

BTU International to Highlight Aurora™ Reflow Technology for Heavy Board and Datacenter PCB Processing at SMTA International

WESTFORD, Mass., September 23, 2026 – BTU International, a leading supplier of advanced thermal processing equipment for the electronics manufacturing and semiconductor packaging markets, will exhibit at **SMTA International 2026**, where the company will highlight its latest **Aurora™** and **Aurora Vacuum™** reflow technologies for heavy board and high-yield applications at **Booth 2729**.

A key focus will be BTU's **Aurora platform**, including the **200N model**, a high-capacity reflow system designed for processing large, heavy printed circuit board assemblies used in AI infrastructure, high-performance computing, networking and datacenter applications.

With high heater power, flexible heating and cooling configurations, and advanced conveyor technologies, the Aurora provides the thermal performance required to process increasingly complex and thermally challenging assemblies. Longer oven configurations and additional zones provide greater control over ramp and cooling rates, while heavy-duty rail designs support the demands associated with processing high-mass boards.



BTU will also showcase its **Aurora Vacuum™ Reflow Oven**, a next-generation vacuum reflow system combining low-void soldering performance with production-ready throughput. Designed

with a large-format vacuum chamber and optional dual-lane operation, Aurora Vacuum enables manufacturers to achieve higher yields while maintaining the productivity required for volume electronics manufacturing.

The Aurora Vacuum platform incorporates several technologies that distinguish it from conventional vacuum reflow systems. An exclusive vacuum soft-start process minimizes component movement and process-induced defects, while integrated heating within the vacuum chamber provides exceptional thermal profile control and process consistency, even for heavy boards. The system's three independent conveyor mechanisms maximize throughput and production flexibility, and its spacious 24.4 x 28.0-inch (620 x 711 mm) vacuum chamber accommodates large-format PCBs commonly used in AI infrastructure, networking and datacenter applications.

Optional dual-lane operation further increases manufacturing productivity, delivering the combination of low-void soldering performance, high throughput and production scalability required for next-generation electronics manufacturing.

“With the rapid growth of AI infrastructure and high-performance computing, our customers are handling larger boards and more complex assemblies than ever before,” said Bob Bouchard, Director of Sales and Marketing for BTU International. “Our Aurora series is purpose-built to meet these demands, offering the thermal power, zone configurability, and profile control needed to achieve reliable solder joints at production scale.”

With decades of experience in thermal processing, BTU works closely with customers to develop reflow solutions that align with specific process requirements, goals and facility constraints. Engineers and manufacturers attending SMTA International are encouraged to visit BTU to learn more about the Aurora and Aurora Vacuum™ systems and discuss their application requirements.

Visit BTU at **Booth 2729** to learn more about the latest Aurora technologies and meet with BTU thermal process experts.

More information about BTU International is available at www.btu.com.

About BTU International

BTU International, a wholly-owned subsidiary of Amtech Group (Nasdaq: ASYS), is a global supplier and technology leader of advanced thermal processing equipment in the electronics manufacturing market. BTU's high-performance reflow ovens are used in the production of SMT printed circuit board assemblies and in semiconductor packaging processes. BTU also specializes in precision controlled, high-temperature belt furnaces for a wide range of custom applications, such as brazing, direct bond copper (DBC), diffusion, and sintering. BTU has operations in Westford, Massachusetts, and Shanghai, China, with direct sales and service in the U.S.A., Asia and Europe. Information about BTU International is available at www.btu.com.

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Company Contact:

Rob DiMatteo

General Manager

BTU International, Inc.

Phone: +1- (978) 667-4111

Media Contact:

Megan Wendling

MW Associates

Phone: +1-(239) 530-8790